

TOSHIBA LED LAMP

TLG211, TLO211, TLR211, TLS211, TLY211

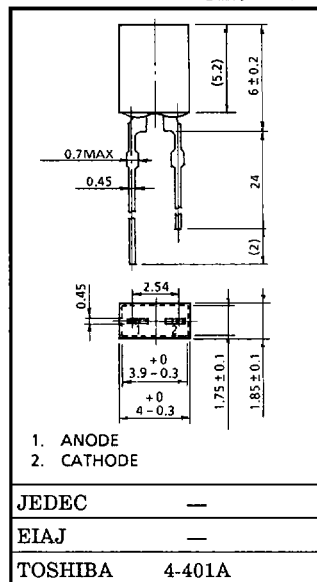
PANEL CIRCUIT INDICATOR

Unit in mm

- All Plastic Mold Type
- Rectangular Type (Surface Size 2×4mm)
- Low Drive Current, High Intensity Light Emission.
Recommended Forward Current : $I_F=10\sim15\text{mA}$ (DC)
- Fast Response Time, Capable of Pulse Operation.

MATERIALS

PRODUCT NAME	MATERIALS	LIGHT EMITTING COLOR
TLG211	GaP	Green
TLY211	GaAsP	Yellow
TLO211	GaAsP	Orange
TLS211	GaAsP	Red
TLR211	GaP	



Weight : 0.12g

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

PRODUCT NAME	FORWARD CURRENT I_F (mA)	REVERSE VOLTAGE V_R (V)	POWER DISSIPATION P_D (mW)	OPERATING TEMPERA- TURE RANGE T_{opr} ($^\circ\text{C}$)	STORAGE TEMPERA- TURE RANGE T_{stg} ($^\circ\text{C}$)
TLG211	25	4	70	$-20\sim75$	$-30\sim100$
TLY211	25	4	70	$-20\sim75$	$-30\sim100$
TLO211	25	4	70	$-20\sim75$	$-30\sim100$
TLS211	25	4	70	$-20\sim75$	$-30\sim100$
TLR211	20	4	56	$-20\sim75$	$-30\sim100$

PRECAUTION

Please be careful of the followings.

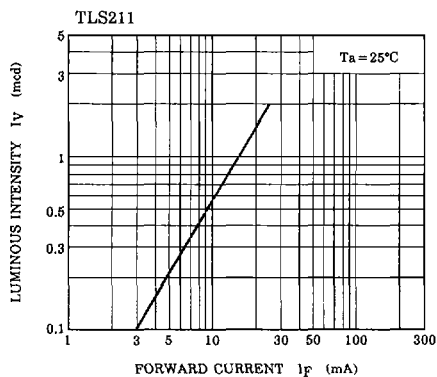
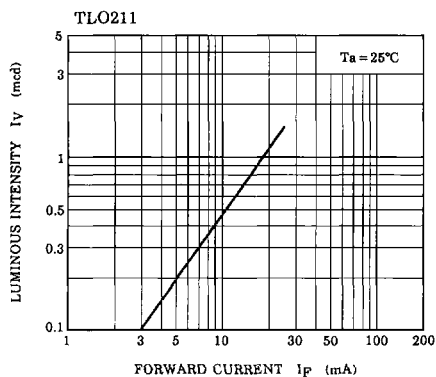
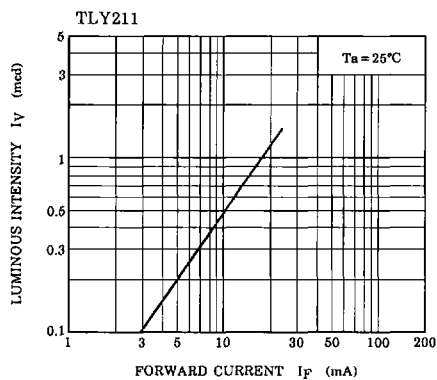
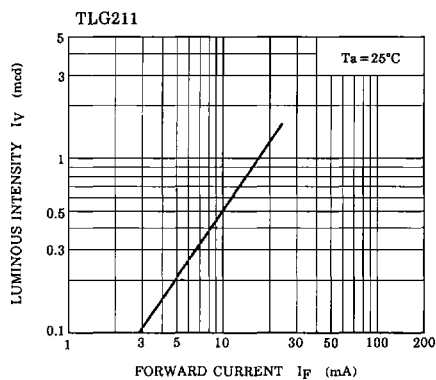
- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

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ELECTRO-OPTICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

PRODUCT NAME	EMISSION SPECTRUM			LUMINOUS INTENSITY I_V			FORWARD VOLTAGE V_F			REVERSE CURRENT I_R	
	λ_p	$\Delta\lambda$	I_F	MIN.	TYP.	I_F	TYP.	MAX.	I_F	MAX.	V_R
TLG211	565	25	10	0.5	1.2	20	2.15	2.8	20	5	4
TLY211	585	32	10	0.5	1.2	20	2.05	2.8	20	100	4
TLO211	610	35	10	0.5	1.2	20	2.05	2.8	20	100	4
TLS211	635	40	10	0.9	1.5	20	2.05	2.8	20	100	4
TLR211	700	100	10	0.5	1.2	20	2.15	2.8	20	5	4
Unit	nm		mA	mcd		mA	V		mA	μA	V

 $I_V - I_F$ 

$I_V - I_F$

